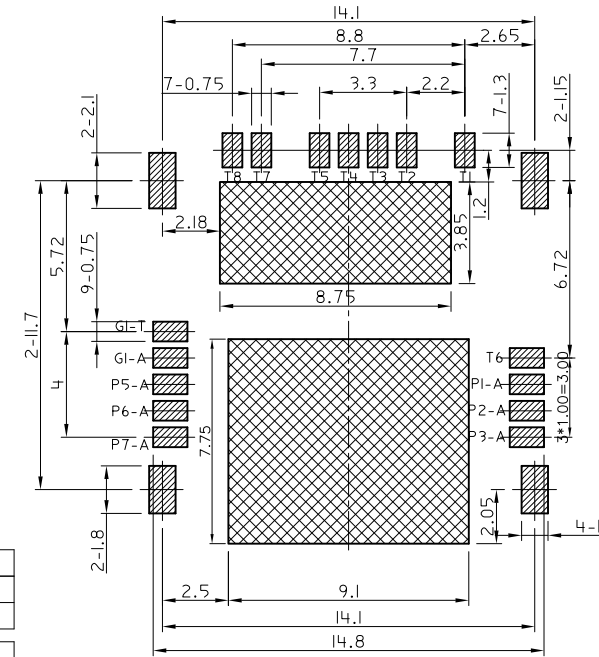
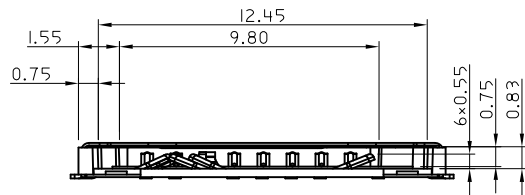
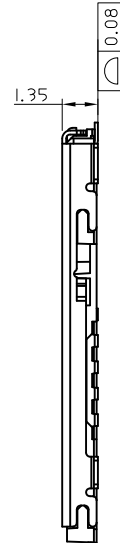
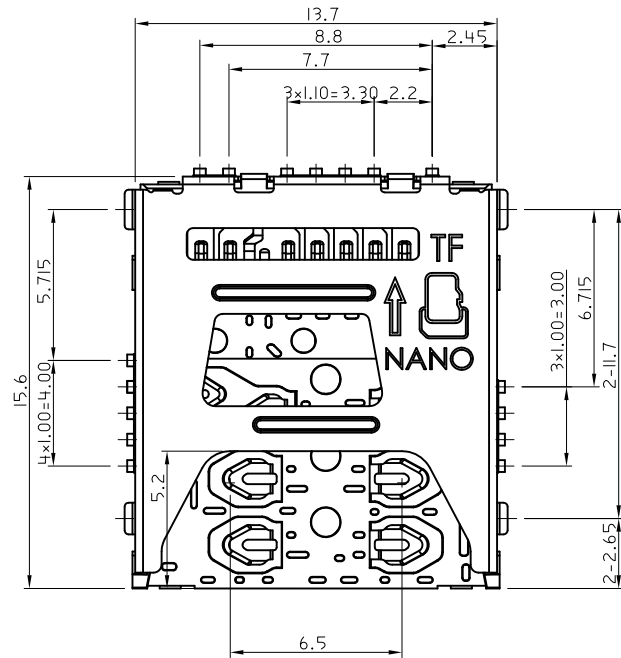


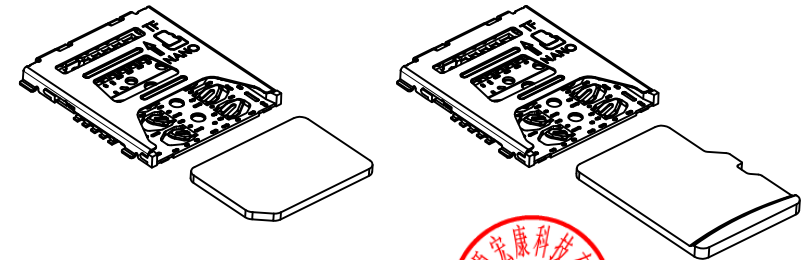
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
▽	PROPOSE ONLY	ALLEN	2015.12.04



RECOMMENDED PCB LAYOUT
(TOLERANCE: ±0.05)

■ SOLDER AREA
▨ NO PATTERNS

Normal OPEN	
T-CARD(without card)	T-CARD(with card)
GI-T → T6	GI-T → T6
Normal OPEN	
SIM-CARD(without card)	SIM-CARD(with card)
GI-A → P5-A	GI-A → P5-A



NOTES:

1. FINISH

- 1-1. HOUSING: LCP, Black.
- 1-2. CONTACT: Hyper Copper Alloy.
CONTACT AREA: Au 15u' min; SW AREA: Au 3u' min;
GOLD PLATING ON SOLDER AREA, 3u' Min.

1-3. SHELL:

SW AREA: 3u' Min.; SOLDER AREA: Au 3u' Min.

2. ELECTRICAL REQUIREMENTS:

- 2-1. CURRENT RATING: 0.5A PER PIN.
- 2-2. CONTACT RESISTANCE: 60mOhm MAX.
- 2-3. INSULATION RESISTANCE: 1000MOhm MIN. 200 VDC FOR 1 MINUTE.
- 2-4. WITHSTANDING STRENGTH: 500V AC FOR 1 MINUTE.

3. MECHANICAL REQUIREMENTS:

- 3-1. TRAY MATING FORCE: 10N MAX.
TRAY UNMATING FORCE: 4N MIN.
OPERATING FORCE: 10N MAX.

3-2. DURABILITY: 2,000 CYCLES MIN.

4. ENVIRONMENT REQUIREMENTS:

- 4-1. OPERATING TEMP.: -30°C TO +85°C
- 4-2. STORAGE TEMPERATURE: -40°C TO +85°C

SIM CARD PIN NO.	PIN NO.	T-CARD PIN NO.	PIN NO.
P1-A	VCC	T1	DAT2
P2-A	RST	T2	CD/DAT3
P3-A	CLK	T3	CMD
P5-A	GND	T4	VDD
P6-A	VPP	T5	CLK
P7-A	I/O	T6	VSS
GI-A	SWITCH	T7	DAT0
		T8	DAT1
		GI-T	SWITCH

UNLESS OTHERWISE
SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.5	X :±2°
X.X :±0.20	X.X :±1°
X.XX :±0.10	

深圳市顺宏康科技有限公司

TITLE	Nano SIM/Micro SD DUAL 2 IN 1 (Combo) CARD CONN.		
DWN	ALLEN	PART NO. TSODL-I30014-I7G	
CHKD	KEVIN	SCALE:1:1	UNIT: mm
APVD	ERIC.W	SIZE: A3	SHEET:1 OF 1
			REV: AI

CUSTOMER COPY